Expert Chemo-Mechanical Polishing (CMP) Solutions

Serving the Silicon Carbide (SiC) and Wide Band Gap Semiconductor Industry

Our focus is you, our customer

We produce coolants, lubricants, abrasive compounds, slurries, and cleaners for use in the machining and finishing of electronic materials and device fabrication.

Our global team of locally available chemists, engineers, and polishing scientists bring their quality assurance expertise to you to enhance your process efficiency.

At our facilities, we maintain

- An R&D laboratory with state-of-the-art analytical equipment.
- A scale-up manufacturing plant.
- Tribological machinery and lapping, polishing, and chemo-mechanical planarizing (CMP) tools.
- High-volume manufacturing capabilities.

Top right photo courtesy of Gigamat, Inc. Bottom photos courtesy of Revasum, Inc. BASF-Chemetall slurries are compatible with all major CMP tool brands.
Enhance wafer and device yield with the precision chemical engineering expertise of Chemetall

At Chemetall, we focus on increasing process efficiency for machining and finishing high-value materials. In the SiC Industry, we understand the challenges that arise when crystals are grown by bulk and epitaxial processes, and the variety of defects that can result. Our goal is to minimize the impact of these defects and maximize your high-quality wafer yields.

After crystal growth, SiC wafers destined for fabrication with RF or Power Devices must be carefully machined, finished, and cleaned. These steps may include:

- Crystal trimming and diameter grind
- Flats grinding
- Wafer slicing
- Edge rounding
- Grinding
- Lapping and polishing
- Chemo-Mechanical Polishing (CMP) — fast, stock removal of bulk material with “zero” damage
- Chemo-Mechanical Polishing (CMP) — Low Ra generation for epi-ready finish
- Cleaning (In-Process and Post CMP)
- Fabricated wafer thinning (backgrind/lap/polish) and dicing

One major focus area is the development of Chemo-Mechanical Polishing (CMP) slurries which deliver near-perfect surfaces on SiC wafers.

<table>
<thead>
<tr>
<th>Process</th>
<th>Slurry</th>
<th>MRR (typical)</th>
<th>Scratch (typical)/mm</th>
<th>Ra (typical)</th>
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<tbody>
<tr>
<td><strong>SIC FACE PARAMETERS</strong></td>
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<tr>
<td>Batch</td>
<td>Sabre® Micropol AF Series</td>
<td>&gt;1.5 μm/hr</td>
<td>&lt;0.2 nm</td>
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<tr>
<td>Single Wafer</td>
<td>Sabre Micropol CS Series</td>
<td>8–10+ μm/hr</td>
<td>&lt;0.2 nm</td>
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<tr>
<td>Final Polish</td>
<td>Sabre Micropol AF2 Series</td>
<td>&lt;2 μm/hr</td>
<td>&lt;0.1 nm</td>
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</table>

Note: All MRR and Ra data are CMP tool operating parameters, polishing pad, and temperature dependent.

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<td><strong>C FACE PARAMETERS</strong></td>
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<tr>
<td>Batch and Single Wafer</td>
<td>Sabre® Micropol CS Series</td>
<td>&gt;15 μm/hr</td>
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Note: All MRR and Ra data are CMP tool operating parameters, polishing pad, and temperature dependent.
Let's enhance your process steps

<table>
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<th>Our expertise</th>
<th>Our full line of products</th>
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| **Crystal Trimming & Diameter Grind** | Coolants — Sabre® Microcut 28S, Tech Cool® 3700  
Cleaners — Sabre Microclean 565 |
| **Flat(s) Grinding** | Coolants — Sabre Microcut 28S, Tech Cool 3700  
Cleaners — Sabre Microclean 565 |
| **Wafer Slicing** | Diamond Powders — Sabre Micropowder D  
Diamond Slurries — Sabre Microlap D  
Vehicle — Sabre Microcut 61V  
Cleaners — Sabre Microclean 565 |
| **Edge Rounding** | Coolants — Sabre Microcut 28S, Tech Cool 3700  
Cleaners — Sabre Microclean 565 |
| **Grinding, Lapping, and Polishing** | Diamond Powders — Sabre Micropowder D  
Diamond Slurries — Sabre Microlap D  
Vehicle — Sabre Microcut 61V  
Cleaners — Sabre Microclean 565  
Polishing Pads — Sabre Pol P |
| **Chemo-Mechanical Polishing (CMP) for Bulk Material Removal, Epi-Ready Finish, and epi-SiC layer** | CMP for Batch Polishing — Sabre Micropol AF Series  
CMP for Single Wafer Polishing (stock removal) — Sabre Micropol CS Series  
CMP for Single Wafer Polishing (final finish and epi) — Sabre Micropol AF2 Series  
CMP Pads — Sabre Pads  
CMP Pad Cleaners — Sabre Pad Clean 185 and 186 |
| **Cleaning (Post-CMP)** | Sabre Microclean 565 |
| **Fabricated Wafer Thinning (Backgrind/Lap/Polish) & Dicing** | Coolants — Sabre Microcut 28S, Tech Cool 3700  
Diamond Powders — Sabre Micropowder D  
Diamond Slurries — Sabre Microlap D  
Vehicle — Sabre Microcut 61V  
Polishing Pads — Sabre Pol P  
Cleaners — Sabre Microclean 565 |

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Chemetall Precision Microchemicals develops and manufactures precision engineered fluids and slurries for the sawing, dicing, grinding, lapping, polishing, and cleaning of a wide spectrum of materials used in high-end technology industries. We take a collaborative approach for product development and are dedicated to solving customers’ material processing challenges.

We are the Surface Treatment global business unit of the Coatings division of BASF, operating under the Chemetall brand, a leading supplier of applied surface treatments and services for metal, plastic, and glass substrates in a vast range of industries and end markets. As process innovators, fully dedicated to your success, we develop, manufacture, and provide best-in-class technologies, systems, and expertise.

Contact Chemetall Precision Microchemicals

Chemetall Precision Microchemicals
46716 Lakeview Blvd.
Fremont, CA 94538
Tel: +1-408-387-5340
Fax:+1-408-809-2883
Email: MicroSalesNA@basf.com

Chemetall GmbH
Trakehner Str. 3
60487 Frankfurt a.M.
Telephone: +49 69 7165 0
Fax: +49 69 7165-3018

Chemetall Asia Pte. Ltd.
12, Loyang Crescent
508980 Singapore
Tel: +65 6885 7900
Fax: +65 6885 7929

Chemetall Chemicals Co., Ltd.
Building 6, Sun Science & Technology Park,
Lane 399 Shengxia Road, Pudong New Area
201210 Shanghai
Telephone: +86 (0) 21-58120929
Fax: +86 (0) 21-58121062

www.ChemetallPrecisionMicrochemical.com

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